



### Pad Coordinates in Microns

1	0; 0	20	-14; 3759	39	3168; 1015
2	0; 171.5	21	-14; 3949	40	3168; 813
3	-14; 421	22	-14; 4151	41	3168; 623
4	-14; 623	23	3168; 4151	42	3168; 421
5	-14; 813	24	3168; 3949	43	3154; 168
6	-14; 1015	25	3168; 3759	44	3154; 1
7	-14; 1205	26	3168; 3557	45	3154; -274.5
8	-14; 1407	27	3168; 3367	46	2736; -274.5
9	-14; 1597	28	3168; 3165	47	2521; -274.5
10	-14; 1799	29	3168; 2975	48	2207.5; -274.5
11	-14; 1989	30	3168; 2773	49	1893.5; -274.5
12	-14; 2191	31	3168; 2583	50	1579.5; -274.5
13	-14; 2381	32	3168; 2381	51	1265.5; -274.5
14	-14; 2583	33	3168; 2191	52	951.5; -274.5
15	-14; 2773	34	3168; 1989	53	655; -274.5
16	-14; 2975	35	3168; 1799	54	360.5; -274.5
17	-14; 3165	36	3168; 1597	55	0; -274.5
18	-14; 3367	37	3168; 1407		
19	-14; 3557	38	3168; 1205		

### HV7224

Pad	Function	Pad	Function	Pad	Function	Pad	Function
1	GND (Power)	16	HV <sub>OUT</sub> 7/34	31	HV <sub>OUT</sub> 32/9	46	V <sub>DD</sub>
2	V <sub>PP</sub>	17	HV <sub>OUT</sub> 6/35	32	HV <sub>OUT</sub> 31/10	47	POL
3	HV <sub>OUT</sub> 20/21	18	HV <sub>OUT</sub> 5/36	33	HV <sub>OUT</sub> 30/11	48	OE
4	HV <sub>OUT</sub> 19/22	19	HV <sub>OUT</sub> 4/37	34	HV <sub>OUT</sub> 29/12	49	DR <sub>IOB</sub>
5	HV <sub>OUT</sub> 18/23	20	HV <sub>OUT</sub> 3/38	35	HV <sub>OUT</sub> 28/13	50	DR <sub>IOA</sub>
6	HV <sub>OUT</sub> 17/24	21	HV <sub>OUT</sub> 2/39	36	HV <sub>OUT</sub> 27/14	51	SHIFT
7	HV <sub>OUT</sub> 16/25	22	HV <sub>OUT</sub> 1/40	37	HV <sub>OUT</sub> 26/15	52	CLK
8	HV <sub>OUT</sub> 15/26	23	HV <sub>OUT</sub> 40/1	38	HV <sub>OUT</sub> 25/16	53	V <sub>DD</sub>
9	HV <sub>OUT</sub> 14/27	24	HV <sub>OUT</sub> 39/2	39	HV <sub>OUT</sub> 24/17	54	DIR
10	HV <sub>OUT</sub> 13/28	25	HV <sub>OUT</sub> 38/3	40	HV <sub>OUT</sub> 23/18	55	GND (Logic)
11	HV <sub>OUT</sub> 12/29	26	HV <sub>OUT</sub> 37/4	41	HV <sub>OUT</sub> 22/19		
12	HV <sub>OUT</sub> 11/30	27	HV <sub>OUT</sub> 36/5	42	HV <sub>OUT</sub> 21/20		
13	HV <sub>OUT</sub> 10/31	28	HV <sub>OUT</sub> 35/6	43	V <sub>PP</sub>		
14	HV <sub>OUT</sub> 9/32	29	HV <sub>OUT</sub> 34/7	44	GND (Power)		
15	HV <sub>OUT</sub> 8/33	30	HV <sub>OUT</sub> 33/8	45	GND (Logic)		

Note:

Pad designation for DIR = H/L

Example: for DIR = H, Pad 3 is HV<sub>OUT</sub>20  
for DIR = L, Pad 3 is HV<sub>OUT</sub>21

## Die Specifications

	mils	mm		
Die Size:	223.23 x 139.37	5.670 x 3.540	Back Side Metal:	None
Die Thickness:	20 ±1	0.50 ±0.02	Back Side Potential:	V <sub>PP</sub>
Bond Pad Size:	4 x 4	0.10 x 0.10	Die Attach Material:	Ablestick 84-1 or equal
Bond Wire Size:	1.3	0.03	Bond Pad Metal:	Al/Si/Cu